

General Description

The WST3423 is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3423 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

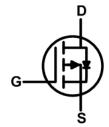
BVDSS	RDSON	ID
-20V	100mΩ	-2.9A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-23N Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	-20	V	
V _{GS}	Gate-Source Voltage	±12	V	
I₀@T₀=25℃	Continuous Drain Current, V _{GS} @ -4.5V ¹ -2.9		A	
I _D @T _c =70℃	Continuous Drain Current, V _{GS} @ -4.5V ¹	-1.9	A	
I _{DM}	Pulsed Drain Current ²	-10	A	
P _D @T _A =25℃	Total Power Dissipation ³	1	W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R _{θJA}	Thermal Resistance Junction-ambient ¹		125	°C/W	
R _{eJC}	Thermal Resistance Junction-Case ¹		80	°C/W	



P-Ch MOSFET

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I _D =-250uA	-20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\!\!\mathbb{C}$, I_D=-1mA		-0.016		V/℃
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-2A		100	130	70 mΩ 20
		V _{GS} =-2.5V , I _D =-1A		145	170	
		V _{GS} =-1.8V , I _D =-1.5A		185	220	
V _{GS(th)}	Gate Threshold Voltage		-0.3	-0.5	-1	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =-250uA		3.97		mV/°C
	Drain Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C V _{DS} =-16V , V _{GS} =0V , T _J =55°C			-1	
I _{DSS}	Drain-Source Leakage Current				-5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 8V$, V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-2A		5.9		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13.1	26.2	Ω
Qg	Total Gate Charge (-4.5V)	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-2A		5.6	7.8	
Q _{gs}	Gate-Source Charge			0.72	1.0	nC
Q _{gd}	Gate-Drain Charge			1.45	2.0	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-15V , V _{GS} =-4.5V , R _G =3.3Ω		4	8.0	
Tr	Rise Time			25.6	46	ns
T _{d(off)}	Turn-Off Delay Time			26	52	
T _f	Fall Time			12.4	24.8	
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		332		
C _{oss}	Output Capacitance			48		pF
C _{rss}	Reverse Transfer Capacitance			42		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}				-2.4	А
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			-10	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V
t _{rr}	Reverse Recovery Time			23		nS
Q _{rr}	Reverse Recovery Charge	l⊧=-2A , dl/dt=100A/µs , TJ=25℃		4.7		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3.The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ $\,$ junction temperature

4.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



P-Ch MOSFET

Typical Characteristics

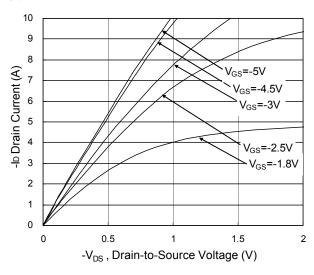


Fig.1 Typical Output Characteristics

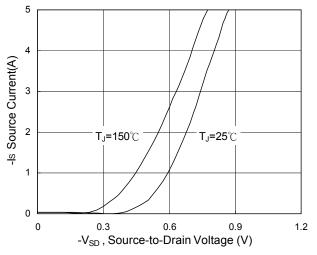


Fig.3 Forward Characteristics Of Reverse

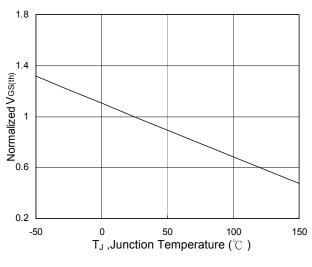


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

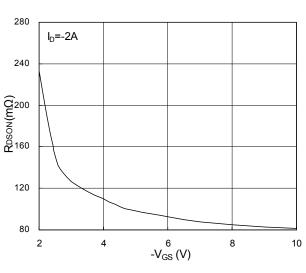


Fig.2 On-Resistance vs. Gate-Source

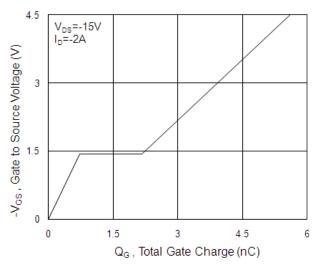


Fig.4 Gate-Charge Characteristics

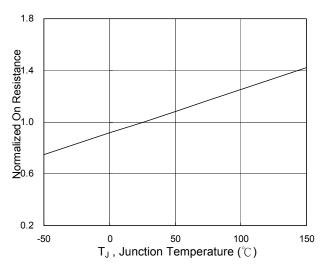
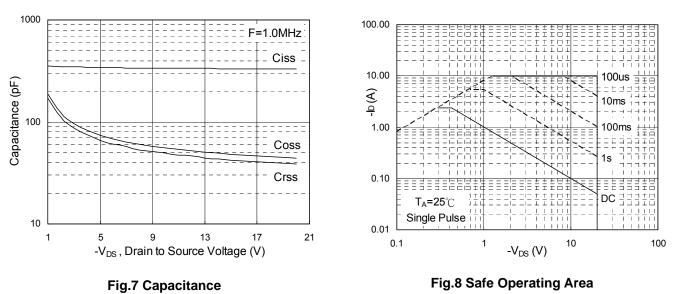


Fig.6 Normalized R_{DSON} vs. T_J



P-Ch MOSFET



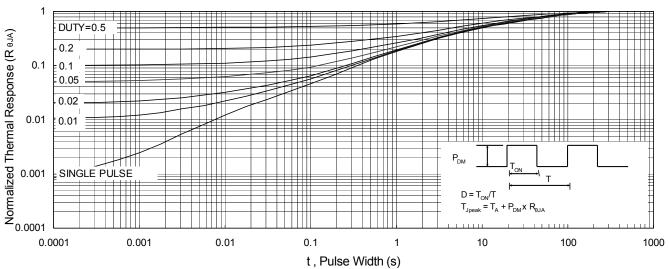


Fig.9 Normalized Maximum Transient Thermal Impedance

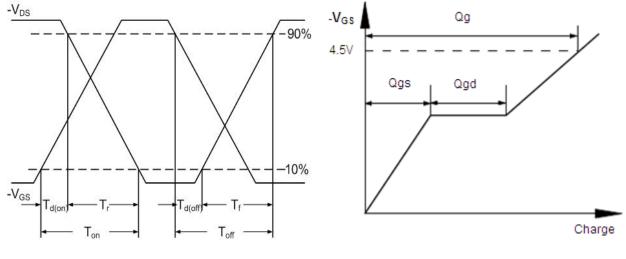




Fig.11 Gate Charge Waveform



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